LNA2902L (LN66A(L))

GaAs infrared light emitting diode

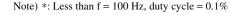
For optical control systems

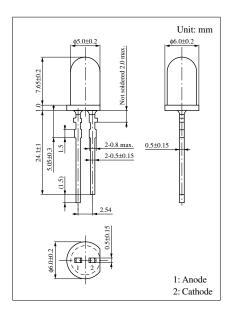
■ Features

- High-power output, high-efficiency: $I_e = 9 \text{ mW/sr (min.)}$
- Emitted light spectrum is suited for silicon photodetectors
- Good radiant power output linearity with respect to input current
- Wide directivity: $\theta = 20^{\circ}$ (typ.)
- Transparent epoxy resin package
- Long lead-wire type

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Symbol Rating	
Power dissipation	P_{D}	160	mW
Forward current (DC)	I_{F}	100	mA
Pulse forward current *	I_{FP}	1.5	A
Reverse voltage (DC)	V _R	3	V
Operating ambient temperature	T _{opr}	-25 to +85	°C
Storage temperature	T_{stg}	-40 to +100	°C





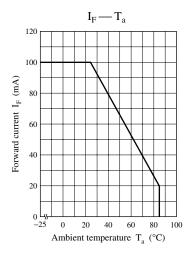
■ Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

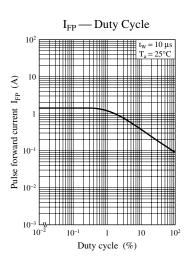
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Radiant intensity	I _e	$I_F = 50 \text{ mA}$	9.0			mW/sr
Total power output	Po	$I_F = 50 \text{ mA}$		12.0		mW
Peak emission wavelength	λ_{P}	$I_F = 50 \text{ mA}$		950		nm
Spectral band width	Δλ	$I_F = 50 \text{ mA}$		50		nm
Forward voltage	V_{F}	$I_F = 100 \text{ mA}$		1.4	1.6	V
Pulse forward voltage *1	V_{FP}	$I_{FP} = 1.0 \text{ A}$			3.0	V
Reverse current	I_R	$V_R = 3 V$			10	μA
Total capacitance between terminals	C _t	$V_R = 0 \text{ V, } f = 1 \text{ MHz}$		35		pF
Beal angle at 50% axial intensity	θ	The angle when the beam intensity is		20		0
		halved.				
Cut-off frequency *2	f_C			1		MHz

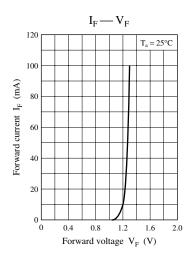
Note) *1: Less than f = 100 Hz, duty cycle = 0.1%

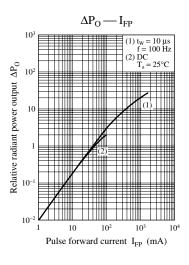
*2: Cut-off frequency
$$f_C$$
: $10 \times log \frac{P_O \text{ at } f = f_C}{P_O \text{ at } f = 50 \text{ kHz}} = -3$

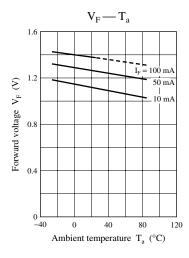
Note) The part number in the parenthesis shows conventional part number.

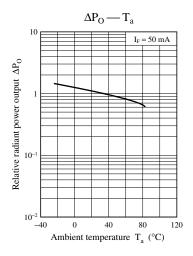


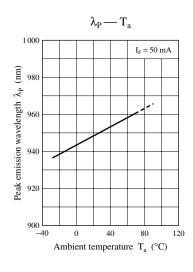


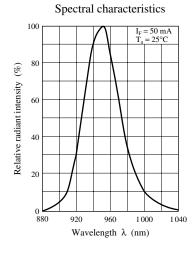


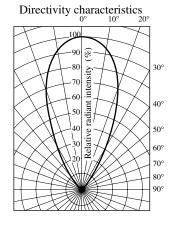




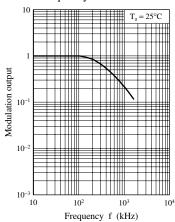








Frequency characteristics



SHC00039AED 3

Caution for Safety



Gallium arsenide material (GaAs) is used in this product.

Therefore, do not burn, destroy, cut, crush, or chemically decompose the product, since gallium arsenide material in powder or vapor form is harmful to human health

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